

Product specifications contained herein may be changed without prior notice. It is therefore advisable to contact Purdy Electronics before proceeding with the design of equipment incorporating this product.

## AND5SA

# GaAsP Bright Red Light Emission Surface Mount Package

#### **Features**

- · Small package size with dome lens
- RoHS Compliant
- 3.2(I) x 2.4 (w) x 2.6 (h) size
- · Suitable for REFLOW soldering
- Recommended Forward Current: 10 mA

#### Maximum Ratings $(T_a = 25^{\circ}C)$

Characteristics	Symbol	Rating	Unit
Forward Current	I <sub>F</sub>	25	mA
Reverse Voltage	V <sub>R</sub>	4	V
Power Dissipation	P <sub>D</sub>	100	mW
Operating Temperature Range	T <sub>Opr</sub>	-30 to 85	°C
Storage Temperature Range	T <sub>Sig</sub>	-30 to 90	°C

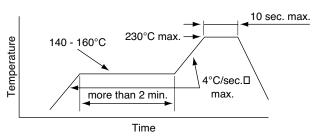
### Electro-Optical Characteristics ( $T_a = 25$ °C)

Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20 mA	_	2.0	2.8	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 4 V	_	-	100	μΑ
Luminous Intensity	I <sub>V</sub>	I <sub>F</sub> = 20 mA	24	40	_	mcd
Peak Emission Wavelength	l <sub>P</sub>	I <sub>F</sub> = 20 mA	_	640	_	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> = 20 mA	_	45	_	nm
Dominant Wavelength	λd	I <sub>F</sub> = 20 mA	_	625	_	nm
Full Viewing Angle	θ	I <sub>V</sub> = 1/2 Peak	_	30	_	degree

#### Precaution

Please be careful of the following:

- Manual soldering: maximum temperature of iron tip: 260°C max.
  Soldering time: within 5 sec. per solder-land
  Soldering portion of lead: up to 1.6 mm from the body of the device
- 2. Reflow solder: recommended condition is as follows:



The following soldering patterns are □ recommended for reflow soldering

